



DCD and Switcher4.2B Tests

21st International Workshop on DEPFET Detectors and Applications, 28.05.-31.05.17 Roberto Blanco (KIT-ADL)

KIT-ADL (ASIC and Detector Laboratory), IPE (Institute of Data Processing and Electronics)









- Switcher4.2B Test Procedure
 - JTAG
 - Test of all gate and clear signals
- DCDIII Test Procedure
 - JTAG
 - Test of ADCs (single, one column, 256 ADCs)
 - Measurement of ADC linearity and noise
- Chip Probe Station
 - Mechanical construction
 - Software control and readout
 - Probe cards for Switcher and DCD
- Test Status and future tests

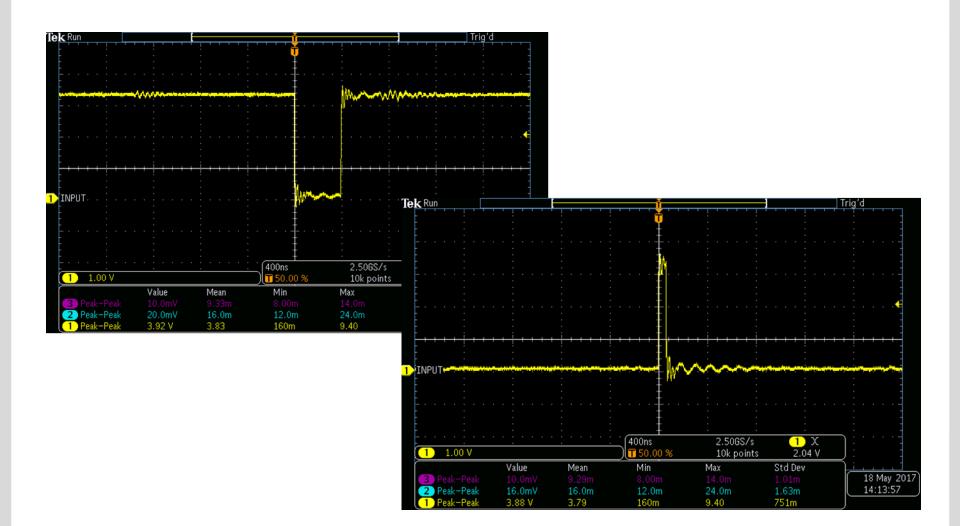




- 1) The chip is contacted
- Following voltages are used: VDD 1.8V, Vgate High = 3.3V, Vclear High = 3.3V, other voltages are zero
- 3) The probe card can contact all Clear and all Gate outputs in total 64
- 4) The outputs are connected to one $64 \rightarrow 1$ "high voltage" MUX
- 5) The output of the multiplexer is connected to a voltage divider (5->1) and to a comparator, it has variable threshold. The threshold is connected to 300 400mV
- 6) The output of the comparator is measured by a scope probe
- 7) JTAG ID test
- 8) The current VDD current consumption versus the DAC value, concerning Clear and Gate current consumption was checked
- 9) Scope measurements of all 64 outputs. A counter is used to increment the channel number, all waveforms are checked
- ** If there is a short between Clear and Gate then would fail and current consumption (Power supply Hameg) would go on











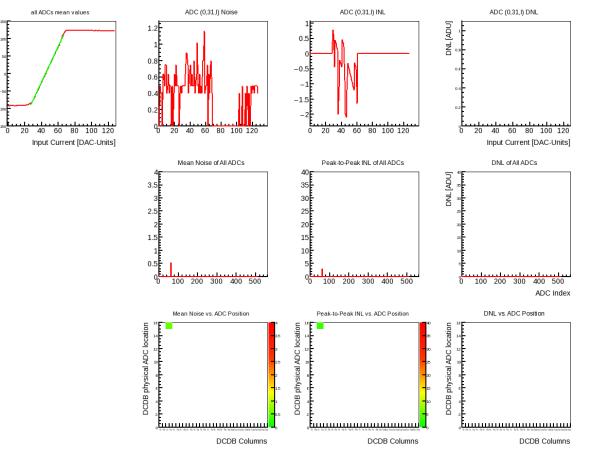
- 1) The chip is contacted
- 2) Following voltages are used VDDD = 1.8V, VDDA = 1.8V, RefIn = 1.1V, AmpLow = 300mV
- 3) In order to check the contact JTAG ID readout, when there is ID then the chuck raising is stopped
- 4) Second test is tests patter readout
- 5) Third test is analog power consumption after DAC configuring
- 6) It happens often that RefIn current is not in the correct range (300mA) after DAC enable
- 7) In this case the chuck is additionally lifted by less then 100um. (Probe station shows the overdrive)
- 8) After this, ADC readout is started
- 9) ADCs are readout via JTAG, 256 are readout is parallel, the test time is so quite short
- 10) For the test, the current source IP_Signal (internal source) is used
- 11) Very often there is a contact problem, the ADC lines does not look nice, in this case usually can be observed that RefIn current oscillates. The chuck is lowered slowly until RefIn current gets stable. Almost always the ADC lines are nice then.
- 12) Our software can measure noise in principle, however for this many points have to be measured per one input. To speed up tests no noise was measured. We observed that noise is very good

DCD-III Test Procedure: Measurements 1



- The figure shows the test of only one ADC. We see also the noise
- The noise is 0.5 and the INL about 2 LSBs

ADU



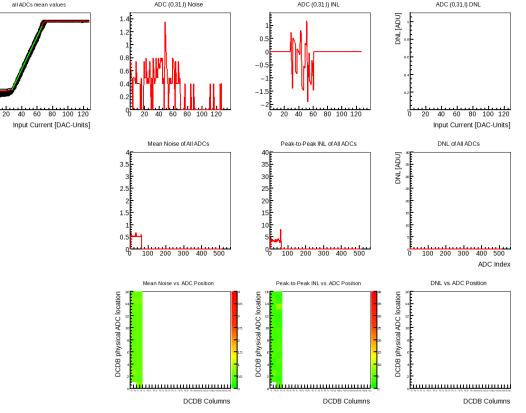
DCD-III Test Procedure: Measurements 2



- Figure show the test of all ADCs in one double column, similar results are obtained
- Here all ADCs in one column are measured at the same time

ADU

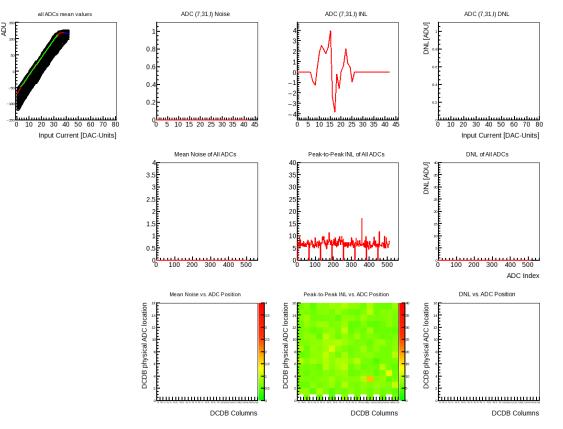
- We have observed that the results are slightly worse when all ADCs (all 8 double-columns)
- The reason is that all VPSignal currents are swept at the same time, therefore the current consumption changes a low and there is a variable voltage drop. This leads to instabilities



DCD-III Test Procedure: Measurements 3



- In order to speed up the tests, we didn't measure the noise
- We think this is not a problem
- Noise can be seen in the INL plot it shows the superposition of noise and INL



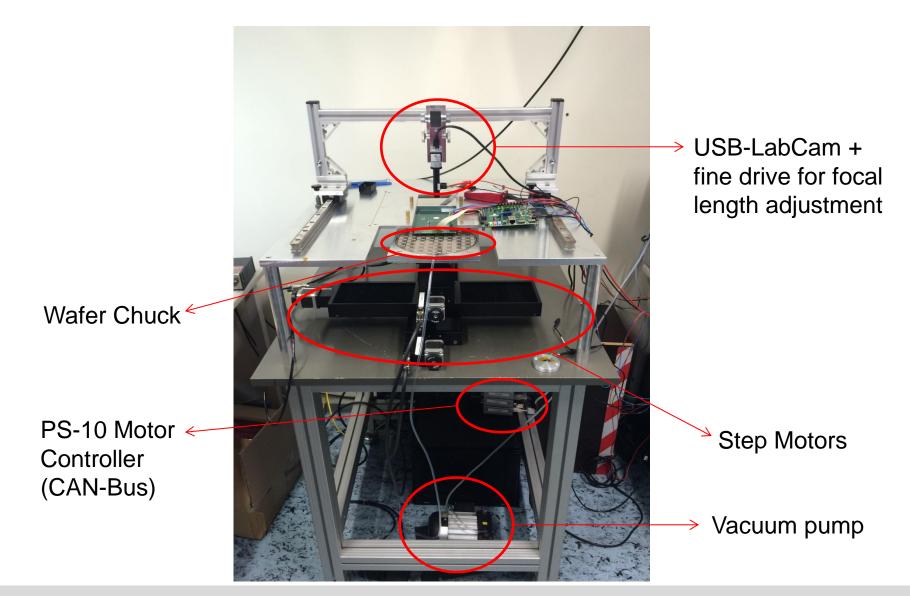




- We have measured ADCs with JTAG
- However we didn't use as we wanted initially the test pads
- The test pads do not have bumps and are places on the top and on the bottom of the chip
- We were able to measure several chips via test pads (see measurement with DCDC), however the time needed to establish contact was too long
- For the measurement with test pads we develop special probe card (PC22)
- Concerning measurements with bumps, we used finally the PC from Heidelberg with a new needle ring
- It showed to be easier to establish contact with this PC than with the PC135
- (JTAG tests work always with all PCs however ADC tests are more difficult)

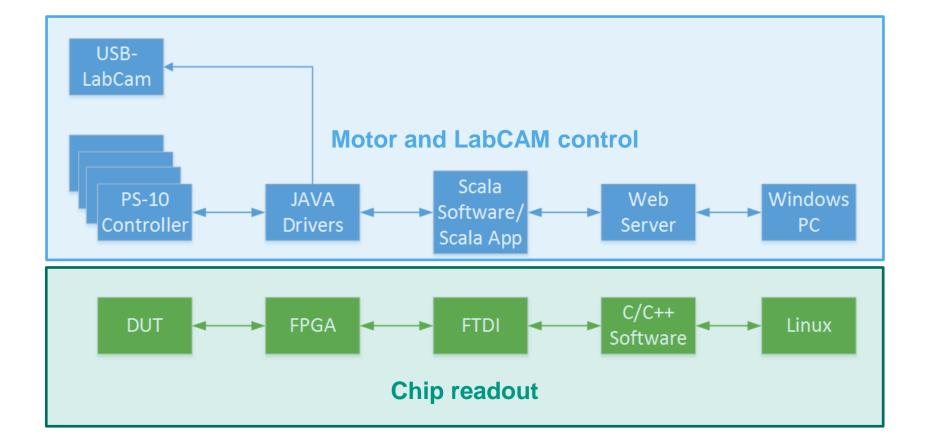
KIT-ADL Chip Probe Station





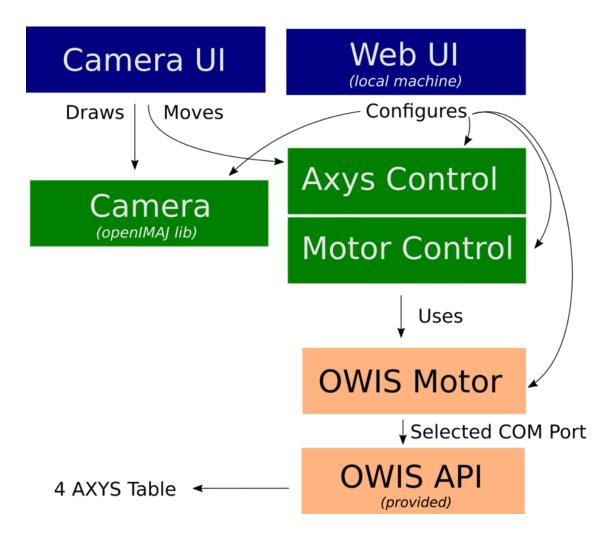






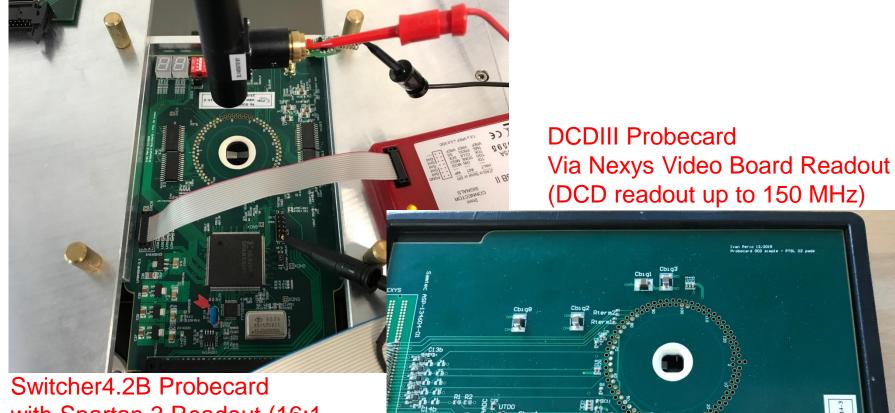
Simplified Block Diagram of the Test Setup





Switcher4.2B and DCD Probecards





with Spartan 3 Readout (16:1 MUX for HV tests)

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Chip Probestation Control Software



☆ 🗾 :

Webserver Application (Axys control)

← → C (i) localhost:8586/probestation/config/axys

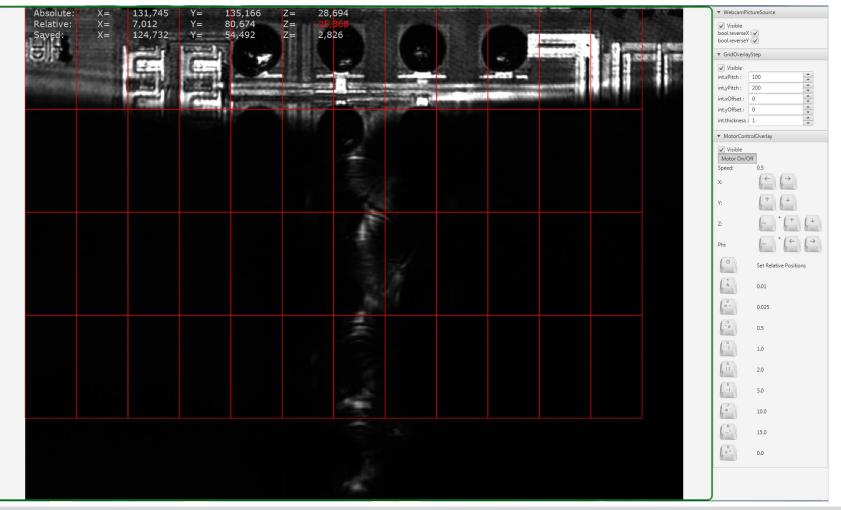
Probestation ::

Switcher4.2B 🗙 🕇		Configura	ation					
Axys -> Ref Stop All	Move A	I to Reference Motor ID	Motor Detected	Exclude from Back to Refere	nce	Back to Zero	Max (mm)	Speed (mm/s)
ashboard	Phi	4 •	Yes	2			9999,0	0,5
tor Configuration	x	1 •	Yes				10000,0	0,5
s Configuration	Y	2 •	Yes				10000,0	0,5
nera Configuration	Z	3 🔻	Yes	•			10000,0	0,5
Motor Control Window								
mentation Config	Axys Name:		Add					
mentation								
Content:	Savec	Position	S					
Configuration	1	lame	Phi	x	Υ		z	Actions
Positions	x 5	witcher4.2B	179,9247	131,703	134,951	5	20,0	Go To Update with Actual
Move Scripts	×s	witcher4.2B Load	179,9247	46,8009	-0,6204		4,6790666666666666	Go To Update with Actual
	Add Posit	on:	Add					
	Auto	Move Scr	ipts					
			Add					

Chip Probesation Control Software 2



Webserver Application (LabCam control)





Chip Probesation Control Software



Chip Readout Software (C/C++)

Activities Mgotest -	Fri 16:01	de 🔻 🗋	∎(x) (b) •
	Switcher-B		×
File			
Write all settings manuell aub GPIB Tests			
Switcher Inputs	-Boundary Scan	ر المراجع	Multiplexer
			A0
☐ Serin	Serin		I A0 □ A1
☐ Strobe Gate	Strobe Gate	Boost Bias Current:	□ A2
☐ Strobe Clear	Strobe Clear	- Com	Г A3
	SerOut		FPGA MUX
			⊑ S0 ⊑ S1
			set
	€ bypass		
32	C SAMPLE/PRELOAD		
Cycle clk:	C EXTTEST		
set	write		
Switcher Outputs			
Switcher Outputs			
SerOut			
read			
	0x23456789		
	G ID ok	G shiftout=shiftin	
	read ID	write	
	read ID	write	
<default config=""></default>			
•	Auto Mode enabled		





TEST STATUS





Switcher Chips	Read JTAG ID	Current Consumption (1.8V/HV)	64 HV- Signals	Bias Current	Boost Current
89	1	1	\checkmark	\checkmark	-
10	\checkmark	\checkmark	*)	\checkmark	\checkmark
1	1	X	X	\checkmark	1

*) It seems a contact problem between needles and switcher. Half of the channels are working!





DCD Chips	Read JTAG ID	Current Consumpti on (VDDA, VDDD)	Digital Test Pattern	Bias Current	Input/Output characteristic
197 (DCDB4.2)	\checkmark	1	1	\checkmark	\checkmark
10 (DCDE-II)					
10 (DCDC)					
10 (DCDEC)					



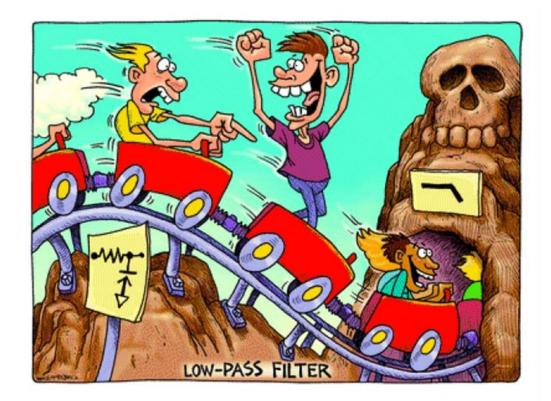


May 2017

- 100 Switchers (already done!)
- 200 DCDs (already done!)
- July 2017
 - 200 Switchers (to do..)
 - 130 DCD (to do..)







Thank you for your attention!